



Initial Product/Process Change Notification

Document #: IPCN25081X

Issue Date: 14 Dec 2022

Title of Change:	Additional wafer fabrication facility, PowerChip located in Taiwan.	
Proposed First Ship date:	22 Jun 2023 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or Jeremy.Ferris@onsemi.com	
PCN Samples Contact:	<p>Contact your local onsemi Sales Office.</p> <p>Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.</p> <p>Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</p>	
Type of Notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com></p>	
Marking of Parts/ Traceability of Change:	Datecode	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Addition	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
None	Powerchip, Taiwan	
Description and Purpose:		
This initial notification is to announce that onsemi will add Powerchip, Taiwan fab to increase production capacity.		
	From	To
Fab Site	Diodes, US	Diodes, US Powerchip, Taiwan
<p>There are no product material changes as a result of this change.</p> <p>There is no product marking change as a result of this change.</p>		



Initial Product/Process Change Notification

Document #: IPCN25081X

Issue Date: 14 Dec 2022

Qualification Plan:

QV DEVICE NAME: FDMF3170, FDMF5071, NCP303152, SCY53601AUC205X, FSA515UCX

RMS: TBD

PACKAGE: PQFN 5x6 / WLCSP

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, Vcc=5.5V	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, Vcc=5.5V	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

Estimated date for qualification completion: 24 March 2023

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FDMF5068	FDMF5071, FDMF3170
FDMF3172	FDMF3170
FDMF3180	FDMF3170
NCP303160MNTWG	NCP303152MNTWG
NCP303152MNTWG	NCP303152MNTWG
FSA515UCX	FSA515UCX
SCY53601AUC205X	SCY53601AUC205X
FAN53611AUC18X	SCY53601AUC205X
FAN53611AUC12X	SCY53601AUC205X
FAN53601UC182X	SCY53601AUC205X
FAN53601AUC105X	SCY53601AUC205X
FDMF5071	FDMF5071
FDMF3170	FDMF3170
FDMF5176	FDMF5071, FDMF3170
FDMF5175	FDMF5071, FDMF3170
FDMF5085	FDMF5071, FDMF3170
FDMF5076	FDMF5071, FDMF3170



Initial Product/Process Change Notification
Document #: IPCN25081X
Issue Date: 14 Dec 2022

FDMF5075	FDMF5071, FDMF3170
FDMF5062	FDMF5071, FDMF3170